SOT222-1

plastic dual in-line package; 24 leads (300 mil)

8 February 2016 Package information

1. Package summary

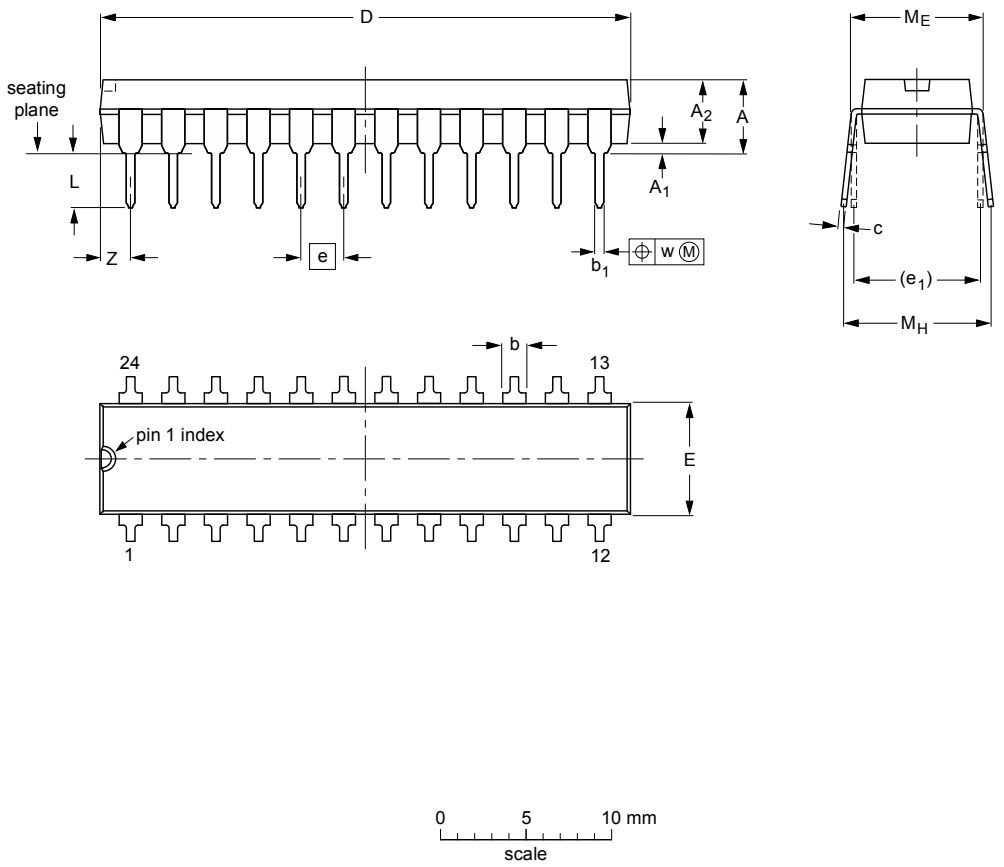
Terminal position code	D (double)
Package type descriptive code	DIP24
Package type industry code	DIP24
Package style descriptive code	DIP (dual in-line package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-001
Mounting method type	T (through-hole mount)
Issue date	12-3-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		31.5	-	31.7	31.9	mm
E	package width		6.25	-	6.49	6.73	mm
A	seated height		[tbd]	-	4.7	4.7	mm
A_2	package height		[tbd]	-	3.94	3.94	mm
n_2	actual quantity of termination		-	-	24	-	

2. Package outline

DIP24: plastic dual in-line package; 24 leads (300 mil) **SOT222-1**



DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.7	0.38	3.94	1.63 1.14	0.56 0.43	0.36 0.25	31.9 31.5	6.73 6.25	2.54	7.62	3.51 3.05	8.13 7.62	10.03 7.62	0.25	2.05
inches	0.185	0.015	0.155	0.064 0.045	0.022 0.017	0.014 0.010	1.256 1.240	0.265 0.246	0.1	0.3	0.138 0.120	0.32 0.30	0.395 0.300	0.01	0.081

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT222-1		MS-001				~~99-12-27~~ 03-03-12

Fig. 1. Package outline DIP24 (SOT222-1)

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